M1MA151WKT1, M1MA152WKT1, SM1MA151WKT1G

Common Cathode Silicon Dual Switching Diodes

These Common Cathode Silicon Epitaxial Planar Dual Diodes are designed for use in ultra high speed switching applications. These devices are housed in the SC–59 package which is designed for low power surface mount applications.

Features

- Fast t_{rr}, < 3.0 ns
- Low C_D, < 2.0 pF
- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- Pb-Free Packages are Available*

MAXIMUM RATINGS (T_A = 25° C)

Rating	Symbol	Value	Unit
Reverse Voltage M1MA151WKT1, SM1MA151WKT1G M1MA152WKT1	V _R	40 80	Vdc
Peak Reverse Voltage M1MA151WKT1, SM1MA151WKT1G M1MA152WKT1	V _{RM}	40 80	Vdc
Forward Current Single Dual	١ _F	100 150	mAdc
Peak Forward Current Single Dual	I _{FM}	225 340	mAdc
Peak Forward Surge Current Single Dual	I _{FSM} (Note 1)	500 750	mAdc

THERMAL CHARACTERISTICS

Rating	Symbol	Max	Unit
Power Dissipation	PD	200	mW
Junction Temperature	TJ	150	°C
Storage Temperature	T _{stg}	–55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

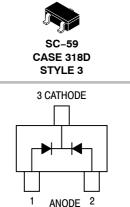
1. t = 1 sec

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

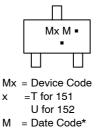
ON Semiconductor®

http://onsemi.com

SC-59 PACKAGE SINGLE SILICON SWITCHING DIODES 40 V/80 V 100 mA SURFACE MOUNT



MARKING DIAGRAM



= Pb-Free Package

(Note: Microdot may be in either location) *Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]				
M1MA151WKT1	SC-59	3,000/Tape & Reel				
M1MA151WKT1G	SC–59 (Pb–Free)	3,000/Tape & Reel				
SM1MA151WKT1G	SC–59 (Pb–Free)	3,000/Tape & Reel				
M1MA152WKT1	SC-59	3,000/Tape & Reel				
M1MA152WKT1G	SC–59 (Pb–Free)	3,000/Tape & Reel				

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

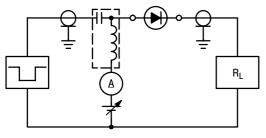
M1MA151WKT1, M1MA152WKT1, SM1MA151WKT1G

ELECTRICAL CHARACTERISTICS (T_A = 25°C)

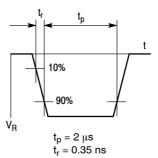
Characteristic	Symbol	Condition	Min	Max	Unit
Reverse Voltage Leakage Current M1MA151WKT1, SM1MA151WKT1G M1MA152WKT1	I _R	V _R = 35 V V _R = 75 V		0.1 0.1	μAdc
Forward Voltage	V _F	I _F = 100 mA	-	1.2	Vdc
Reverse Breakdown Voltage M1MA151WKT1, SM1MA151WKT1G M1MA152WKT1	V _R	I _R = 100 μA	40 80		Vdc
Diode Capacitance	CD	V _R = 0, f = 1.0 MHz	-	2.0	pF
Reverse Recovery Time (Figure 1)	t _{rr} (Note 2)	$ I_F = 10 \text{ mA}, \text{V}_\text{R} = 6.0 \text{ V}, \\ \text{R}_\text{L} = 100 \ \Omega, \text{I}_\text{rr} = 0.1 \text{I}_\text{R} $	-	3.0	ns

2. t_{rr} Test Circuit

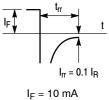
RECOVERY TIME EQUIVALENT TEST CIRCUIT



INPUT PULSE







 $V_{\rm R} = 10 \, {\rm mA}$ $V_{\rm R} = 6 \, {\rm V}$ $R_{\rm L} = 100 \, {\Omega}$



M1MA151WKT1, M1MA152WKT1, SM1MA151WKT1G

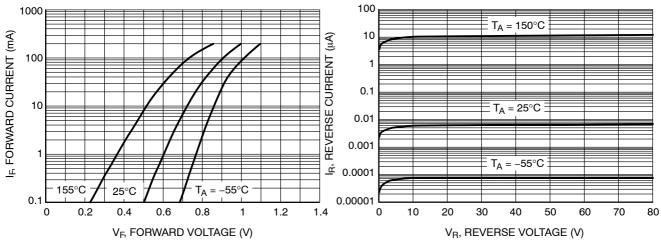
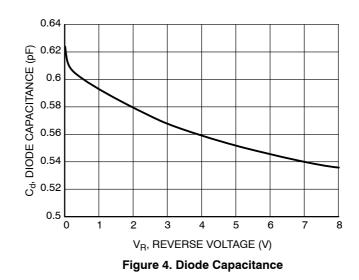




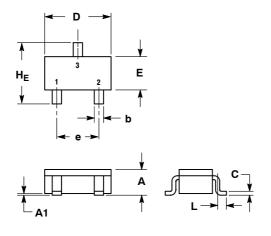
Figure 3. Reverse Leakage



M1MA151WKT1, M1MA152WKT1, SM1MA151WKT1G

PACKAGE DIMENSIONS

SC -59 CASE 318D -04 ISSUE H



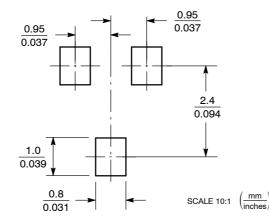
NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.00	1.15	1.30	0.039	0.045	0.051
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.35	0.43	0.50	0.014	0.017	0.020
c	0.09	0.14	0.18	0.003	0.005	0.007
D	2.70	2.90	3.10	0.106	0.114	0.122
Е	1.30	1.50	1.70	0.051	0.059	0.067
e	1.70	1.90	2.10	0.067	0.075	0.083
L	0.20	0.40	0.60	0.008	0.016	0.024
ΗE	2.50	2.80	3.00	0.099	0.110	0.118

STYLE 3: PIN 1. ANODE

2. ANODE 3. CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb -Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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